

Silicone Heat Transfer Compound

860 is a thermal paste designed to reduce thermal resistance between irregular metal surfaces. Coupled with reasonable thermal conductivity, it has a soft consistency and a wide operating temperature range, making it an ideal thermal paste for CPU applications.

This silicone-based thermal paste is mostly used to improve heat flow between heat sinks and heat-generating components, such as CPUs, GPUs, LEDs, motors, and power components.

Features & Benefits

High dielectric strength

Excellent corrosion resistance

Non-bleeding heat transfer paste

Non-electrically conductive

Long service life

Storage and Handling

Store between 0 and 27 °C in a dry area, away from sunlight (see SDS).

Properties

Color	White	—
Filler	Zinc oxide	—
Base Material	Silicone oil	—
Density	2.4 g/mL	ASTM D1475
Viscosity @ 25 °C	490 Pa·s	Brookfield Engineering labs Inc. IPCTM-65- Method 2.4.24.4
Resistivity	$1.5 \times 10^{15} \Omega \cdot \text{cm}$	ASTM D257
Thermal Conductivity @ 25 °C	0.7 W/(m·K)	Hot Wire Method
Evaporation Loss, 22 h @ 165 °C	0.1 %	ASTM D2595
Oil Separation, 30 h @ 165 °C	0.7 %	ASTM D6184
Worked Penetration, ½ scale	303	ASTM D217
Water Washout @ 38 °C Bearing Dried @ 77 °C	0.1 %	ASTM D1264
Dielectric Strength	400 V/mil	ASTM D149
Dielectric Constant	3.8	ASTM D150
Dissipation Factor	0.003	ASTM D150
Service Temperature Range	-40–200 °C	—
Shelf Life	5 y	—



Available Packaging

Part #	Package	Net Vol.	Net Wt.
860-4G	Pouch	1.7 mL	4 g
860-60G	Jar	25 mL	60 g
860-150G	Tube	62.5 mL	150 g
860-1P	Jar	470 mL	1.13 kg
860-6KG (MTO)	Pail	5.4 L	12.9 kg

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